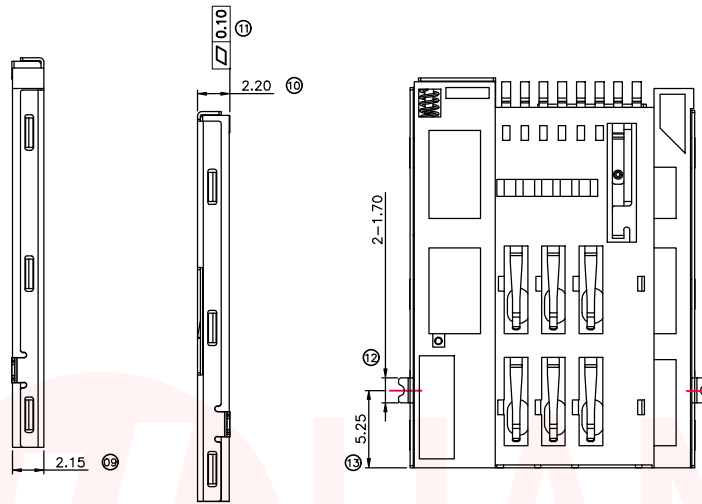
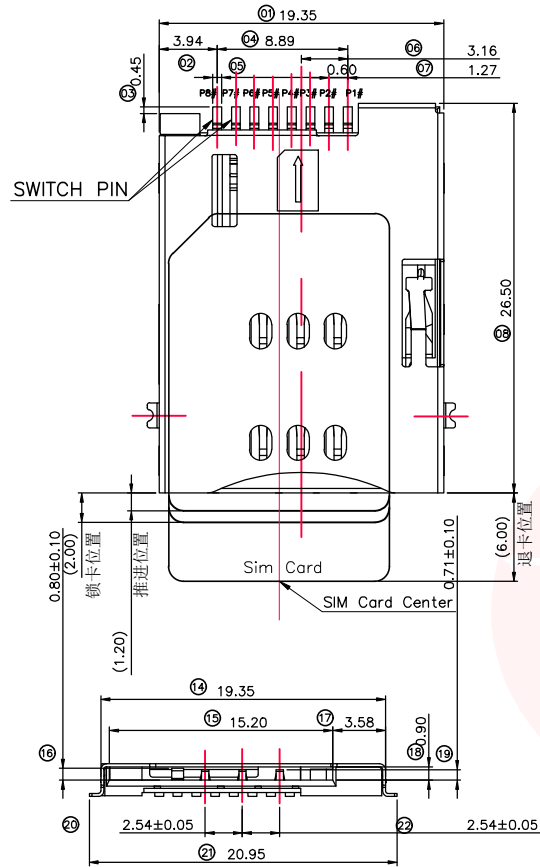


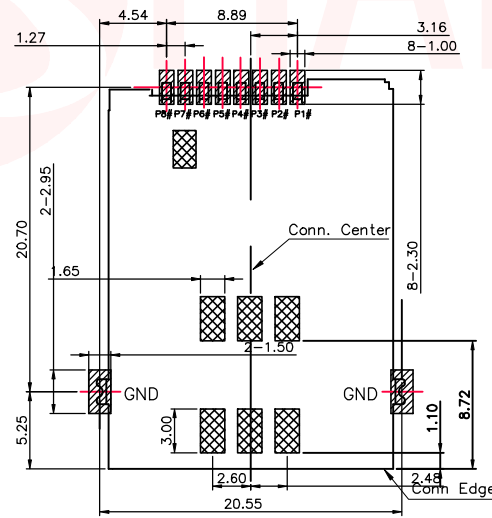
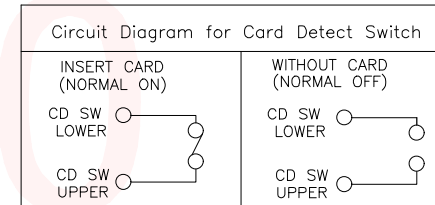
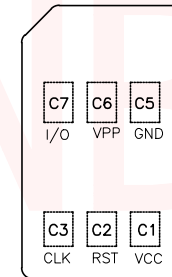


REV.	ECN NO OR DESCRIPTION	REVISED	DATE



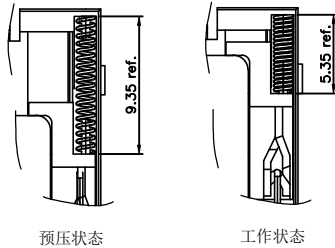
NOTES:

- MATERIAL:
HOUSING: LCP UL 94V-0
CONTACT: C5210R-H,T=0.15
SHELL: SUS201,T=0.15
MYLAR: POLYESTER
- FINISH :
CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATING ON SOLDER TAILS, WITH
ENTIRE CONTACT UNDERPLATED 30u"Min. NICKEL
SHELL: 50u"Min. NICKEL UNDERPLATED OVERALL ,
GOLD FLASH PLATED ON SOLDER TAILS
- INFRARED REFLOW SOLDERING: 10sec. Min. at 260±10



SIM 示意图
芯片面朝下视图

PIN NO.	DESCRIPTION
P1#	C1:VCC
P2#	C5:GND
P3#	C2:RST
P4#	C6:VPP
P5#	C3:CLK
P6#	C7:I/O
P7#	POL
P8#	DET



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

- SOLDER AREA
- NONE CIRCUIT DIAGRAM AREA

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.45	X :±2°
X.X :±0.35	X.X :±1°
X.XX :±0.25	

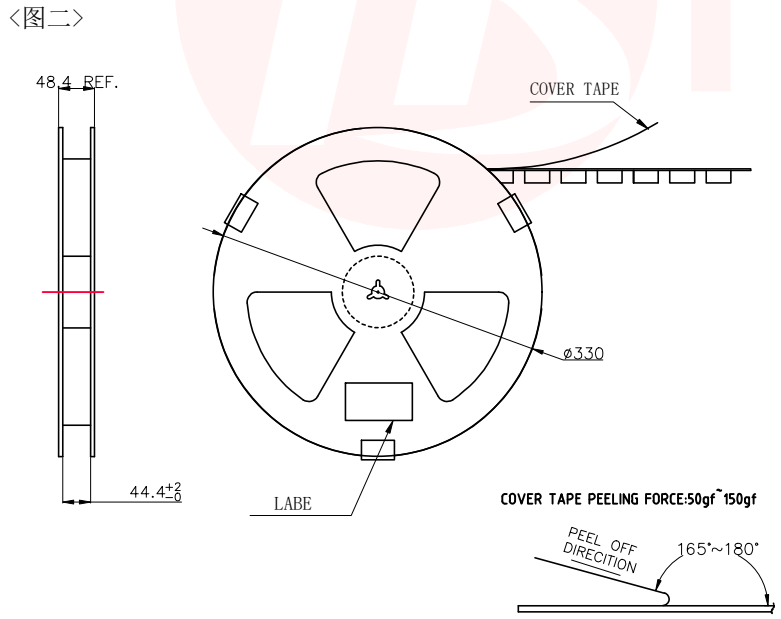
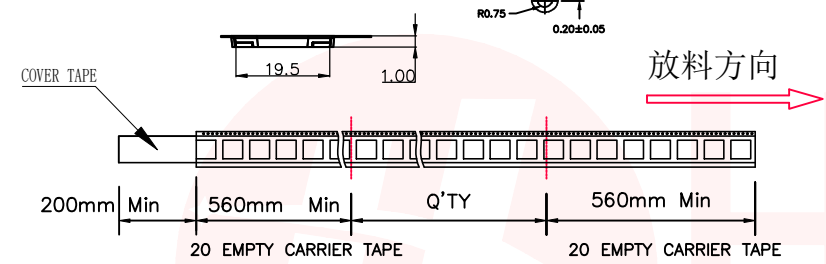
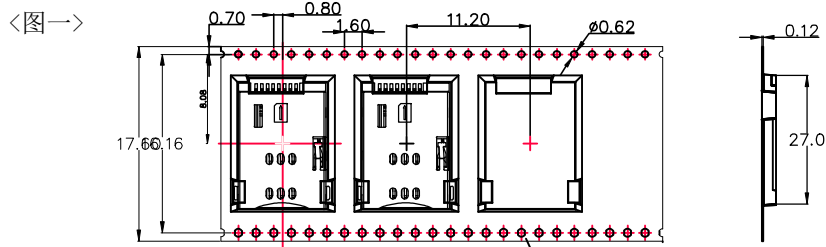


东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	PUSH SIM CARD 6+2PIN 2.20H 脚距5.25无柱		
DWN	xiong	PART NO. SIM-1005-P8	
CHKD	lee	SCALE:1:1	UNIT: mm
APVD	wang	SIZE: A4	SHEET:10F 1 REV: A4
CUSTOMER COPY			



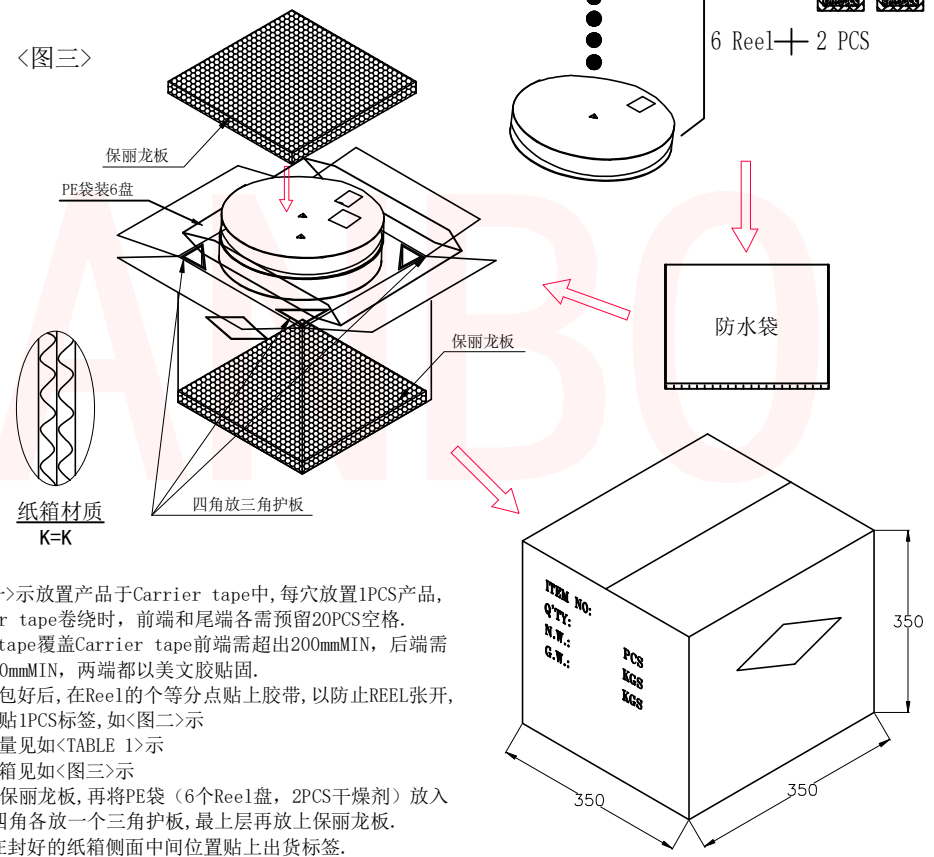
REV.	ECN NO OR DESCRIPTION	REVISED	DATE



<TABLE 1> PACKAGING QUANTITY

QTY/REEL	REEL/CARTON	QTY/CARTON
550	6	3300

<图三>



备注:

1. 依<图一>示放置产品于Carrier tape中,每穴放置1PCS产品, Carrier tape卷绕时,前端和尾端各需预留20PCS空格.
2. Cover tape覆盖Carrier tape前端需超出200mmMIN, 后端需留出300mmMIN, 两端都以美文胶贴固.
3. 包装机包好后,在Reel的个等分点上贴胶带,以防止REEL张开,每Reel贴1PCS标签,如<图二>示
4. 包装数量见如<TABLE 1>示
5. 包装成箱见如<图三>示
箱底放保利龙板,再将PE袋(6个Reel盘,2PCS干燥剂)放入箱内,四角各放一个三角护板,最上层再放上保利龙板.
6. 封箱,在封好的纸箱侧面中间位置贴上出货标签.

纸箱材质
K=K

UNLESS OTHERWISE SPECIFIED TOLERANCES		东莞市汉博电子科技有限公司 DONGGUAN HANBO TECHNOLOGY CO., LTD			
DECIMALS:	ANGLES:	TITLE: PUSH SIM CARD 6+2PIN 2.20H 脚距5.25无柱			
X :±0.45	X :±2°	DWN	xiong	PART NO. SIM-1005-P8	
X.X :±0.35	X.X :±1°	CHKD	lee	SCALE: 1:1	UNIT: mm
X.XX :±0.25		APVD	wang	SIZE: A4	SHEET: 10F 1
		REV: A4			
CUSTOMER COPY					